



INTERNATIONAL ELECTRIC VEHICLE SYMPOSIUM & EXHIBITION



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DC-Link Capacitor Packaging and Thermal Management for 48-V Hybrid Passenger Vehicles

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Outline



1. Introduction (3-driven factors for 48v MHV market)

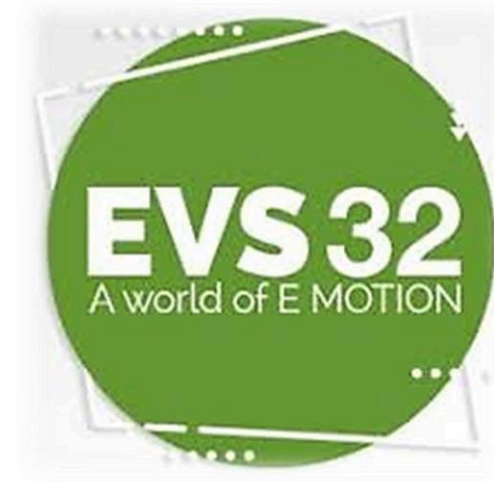
- ✓ Hybrid System
- ✓ New Concept Bus-Bar

2. Thermal Management (Thermal Behavior)

- ✓ Single Capacitor (Modeling, Thermal Sim. and Expt.)
- ✓ Bus-Bar Heat Generation (Thermal Sim. and Expt.)
- ✓ Change in Copper Thickness of Bus-Bar
- ✓ Influence of Heat Conduction from Bus-Bar
- ✓ C-Module Heat Generation (Thermal Sim. & Expt.)
- ✓ Outcome with Suitable Thermal Management

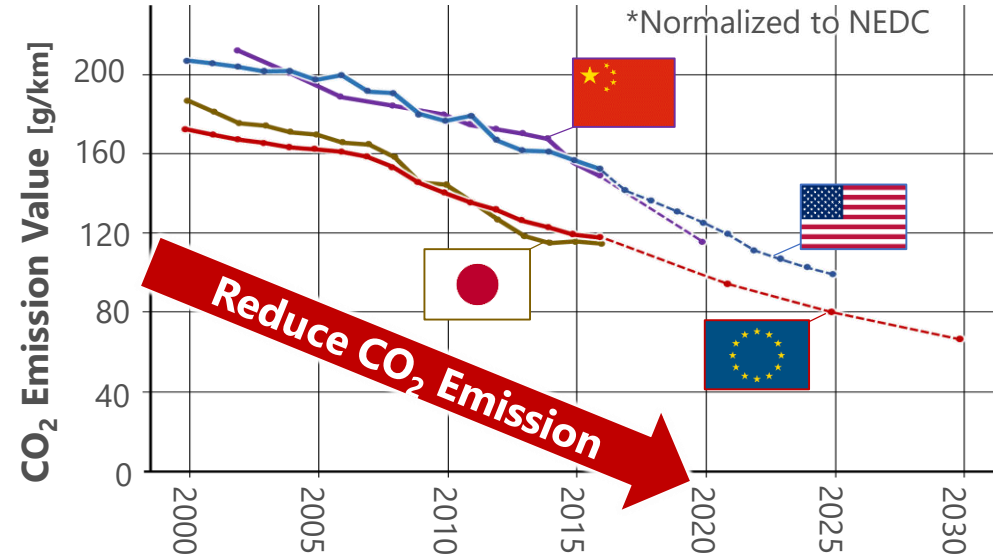
3. Life Analysis (Predicted Life at Worst Case Study)

4. Conclusions



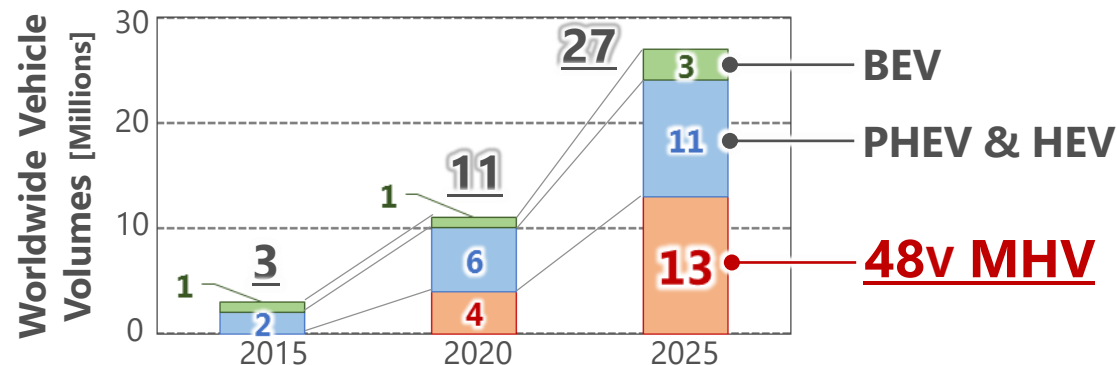
1. Introduction (3-driven factors for 48v MHV market)

● CO₂ Emission Regulation



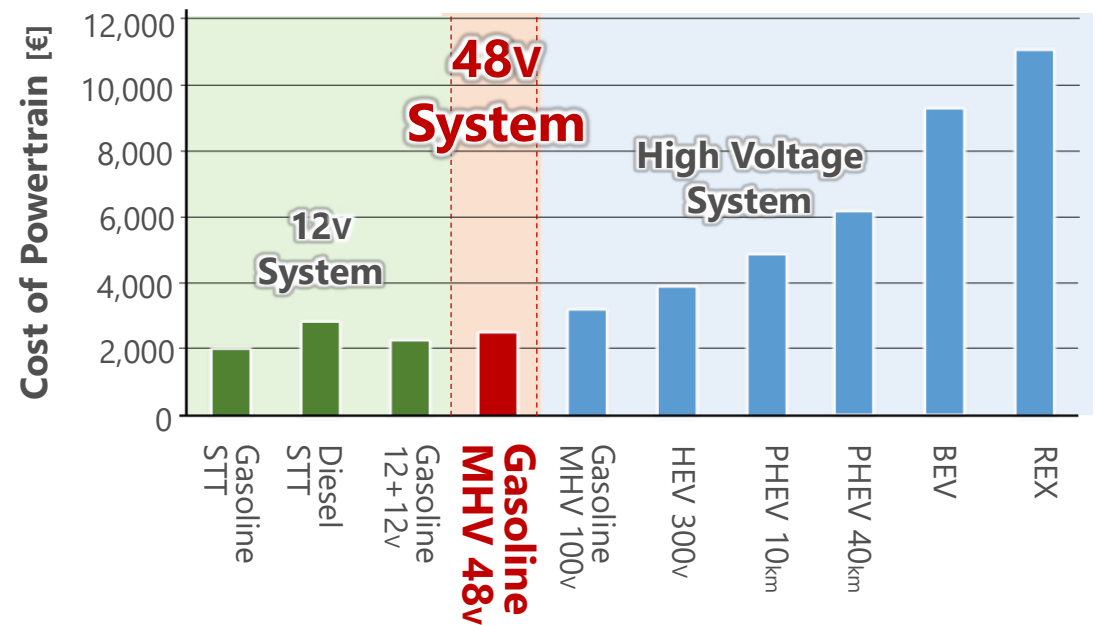
*Source: Own illustration of data from
"https://www.theicct.org/chart-library-passenger-vehicle-fuel-economy"

● 48v MHV will be approx. 50% by 2025



*Source: Own illustration of data from
"Continental at Driven Innovation Workshop Washington, DC September 2016"

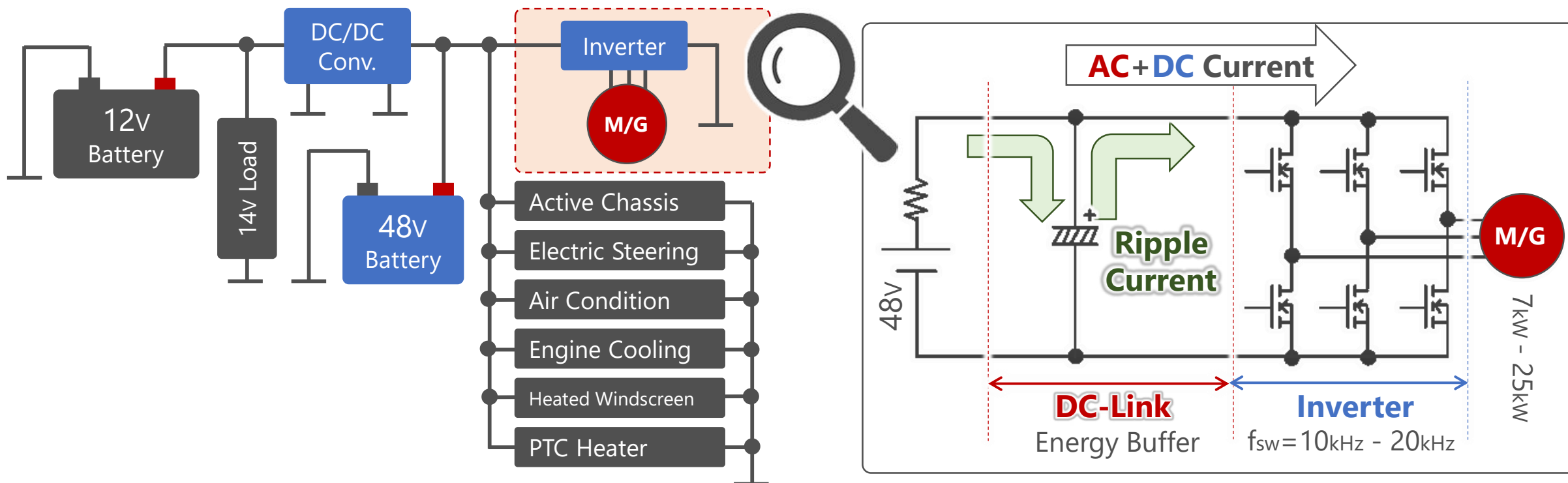
● Better Cost Performance



*Source: Own illustration of data from "Valeo at 4th International Conference Automotive 48V Power Supply System Berlin, 29-30 November 2016"

1-1. Hybrid System

● DC-Link Capacitor Module for 48v MHV System



AC Current
(100Arms-300Arms)

& DC Current
(100Adc-500Adc)

Heat Generation

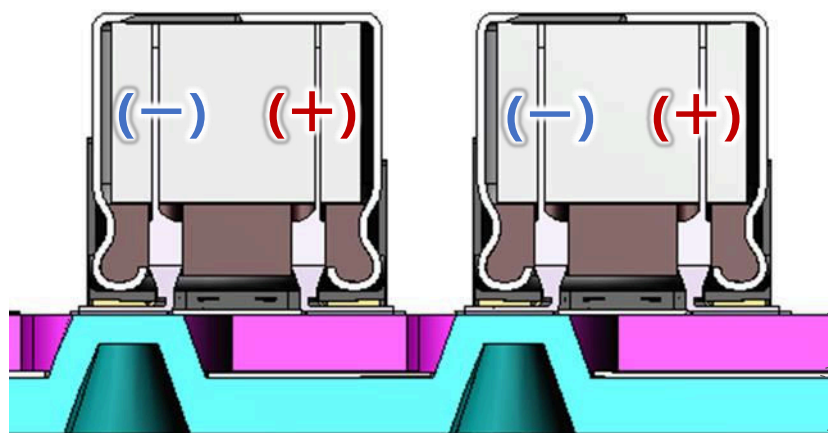
1-2. New Concept Bus-Bar

● C-Module (Capacitor Module Packaging)

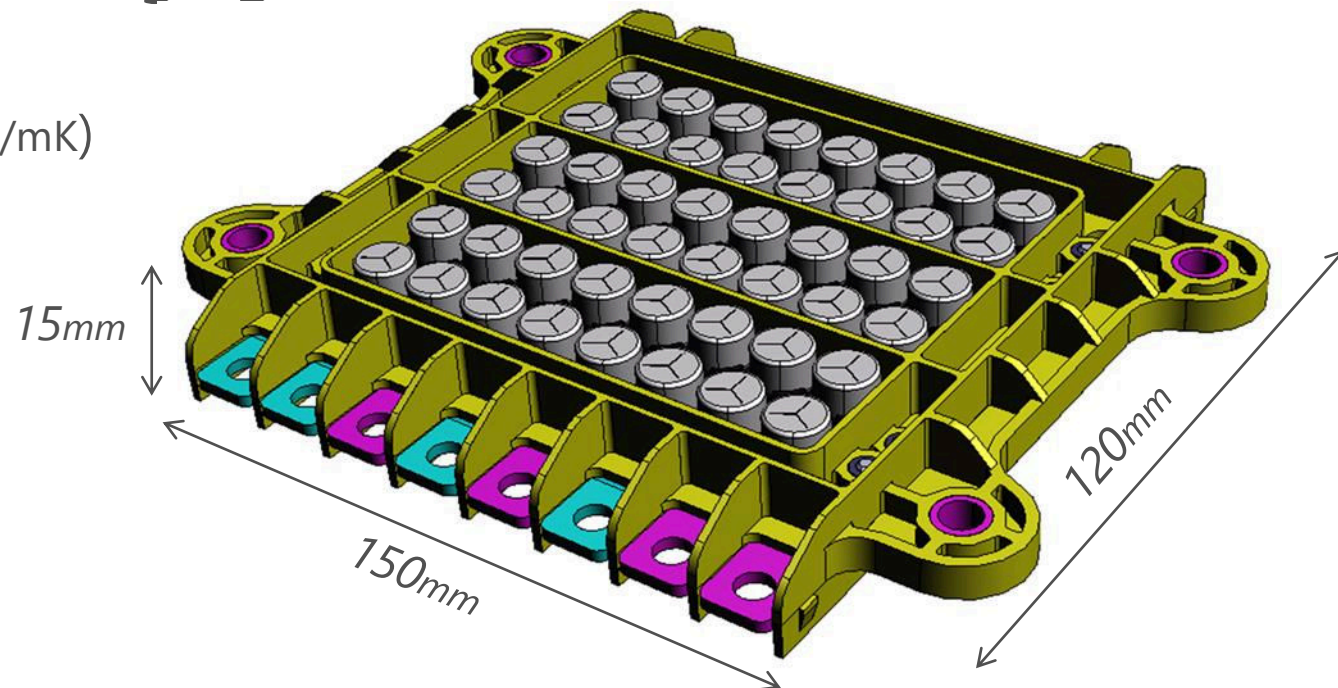
(ex. Mounted 48pcs. Parallel Capacitors)

- ✓ High Heat Conduction (Cu: 372W/mK)
- ✓ Low Resistance ($0.8\text{m}\Omega$ / 10kHz)
- ✓ Low Inductance (5.4nH / 1MHz)

HXC-series SMD HYB-Capacitor
(63V82 μ F, $\phi 10 \times 10\text{L}$, Nippon Chemi-Con)



*Patent Pending: 2018-107427



C-Module

Positive Bus-Bar
(2mm thick Copper)

Insulated Sheet
(200 μ m thick film)

Negative Bus-Bar
(2mm thick Copper)

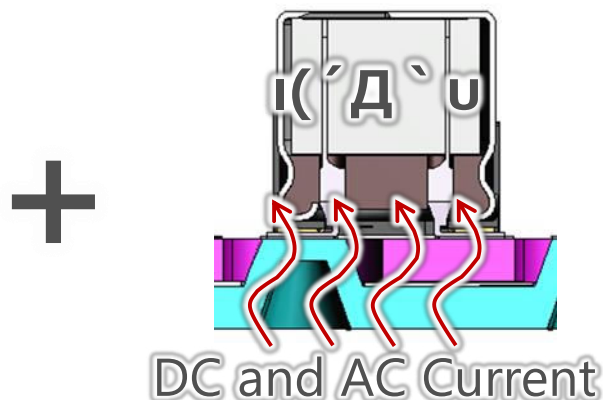
2. Thermal Management (Thermal Behavior)

● Three key points for suitable solution of “Thermal Management”

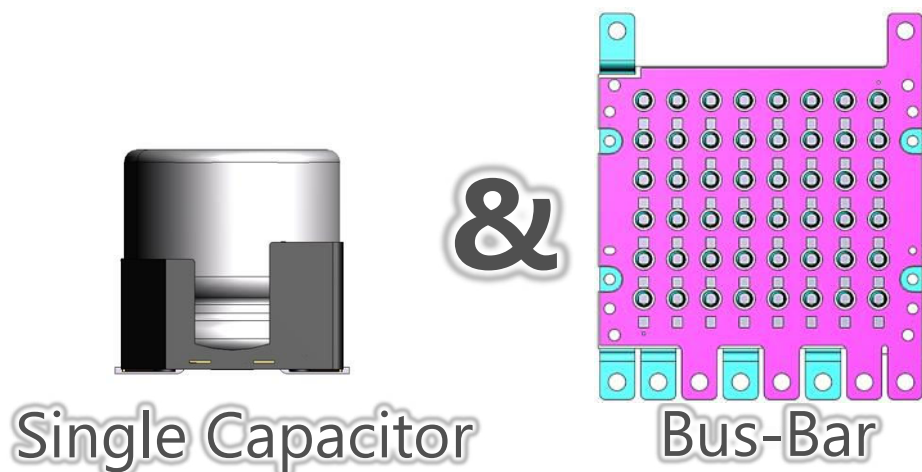
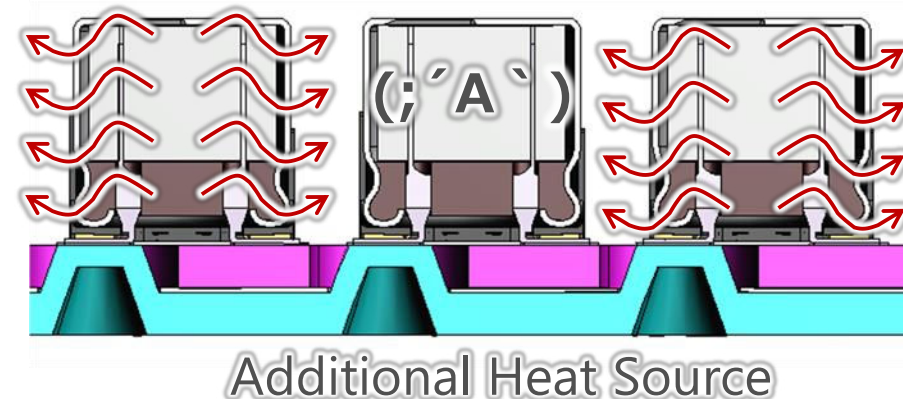
1. Self-Heating



2. Heat Conduction



3. Heat Radiation/Convection (Air-flow)

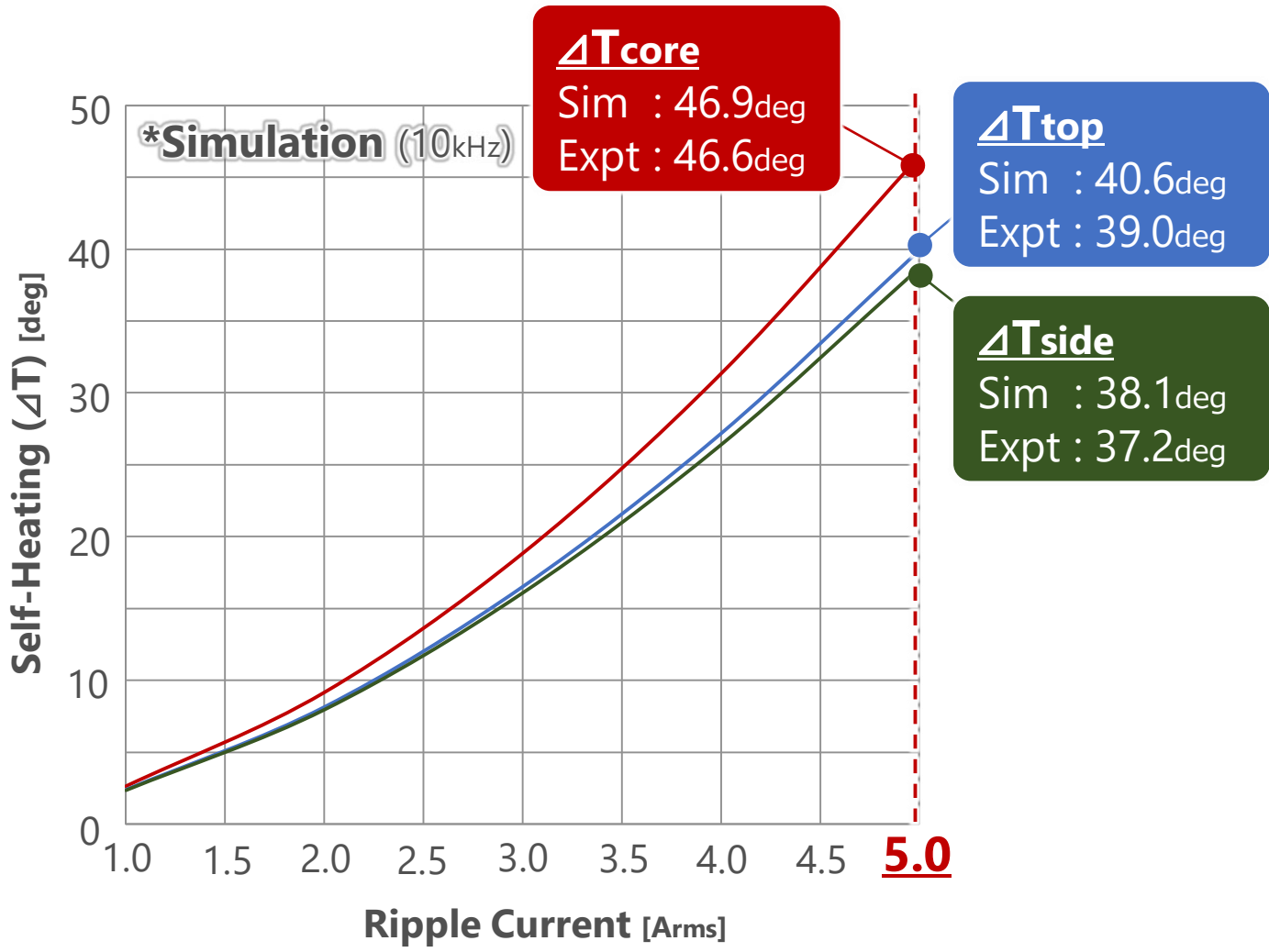
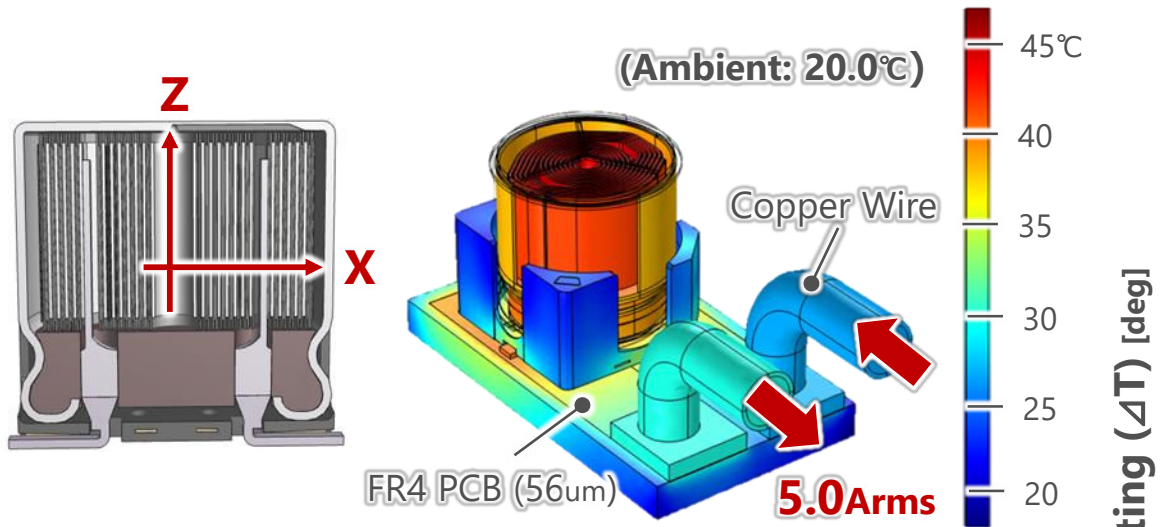


● **Understanding thermal behavior**

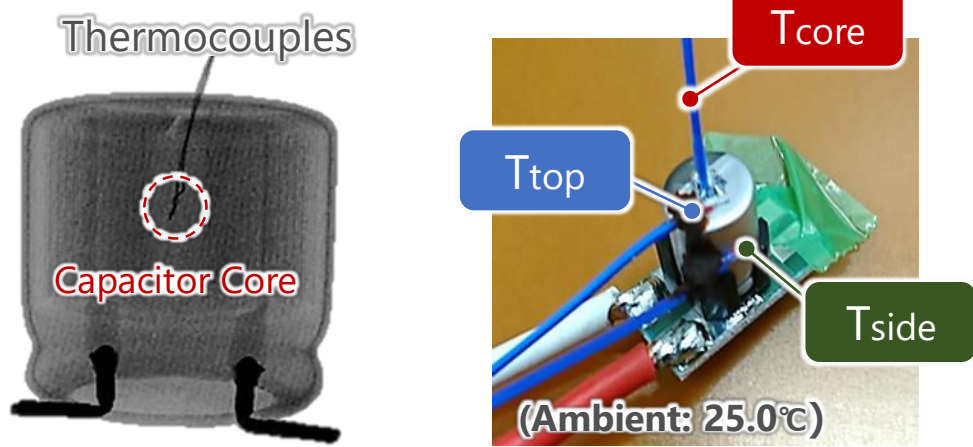
- ✓ Single-capacitor and bus-bar modeling.
- ✓ Fine tuning of simulation parameters.
- ✓ Comparison of thermal Sim. & Expt.
- ✓ Confirm accuracy of thermal Sim. & Expt.

2-1. Single Capacitor (Modeling, Thermal Sim. & Expt.)

● Simulation



● Experiment

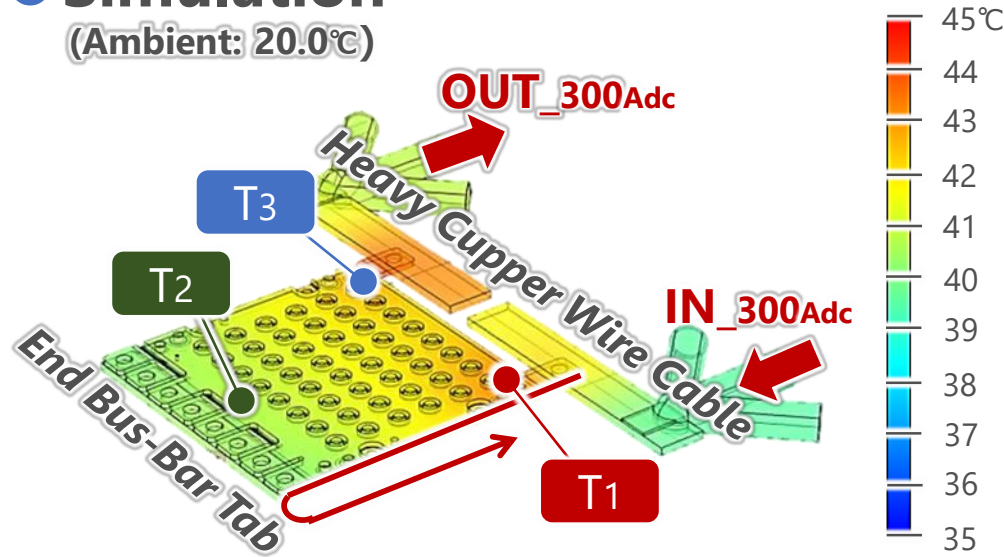


✓ Sim. & Expt. agree each other quite well.

2-2. Bus-Bar Heat Generation (Thermal Sim. & Expt.)

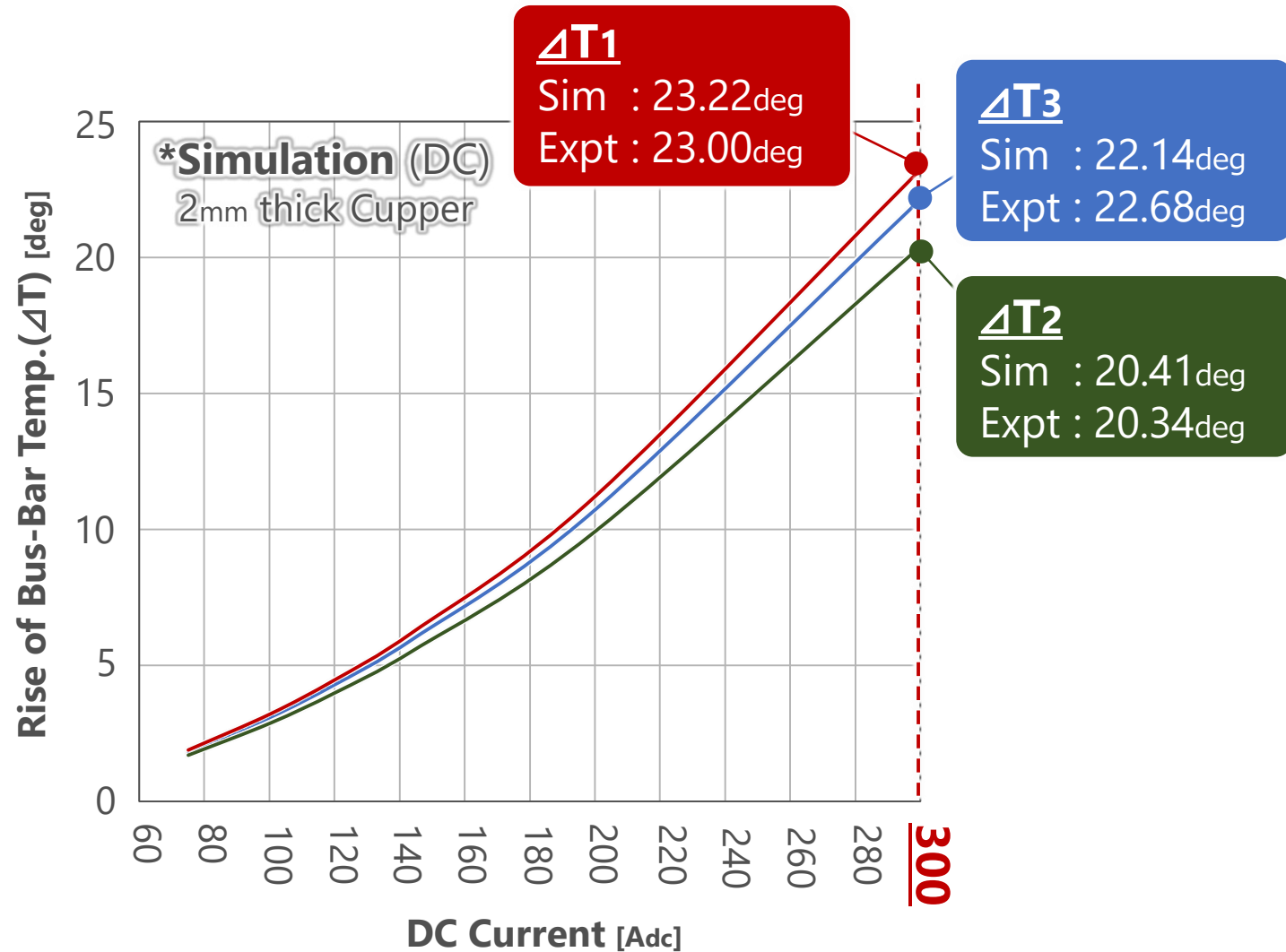
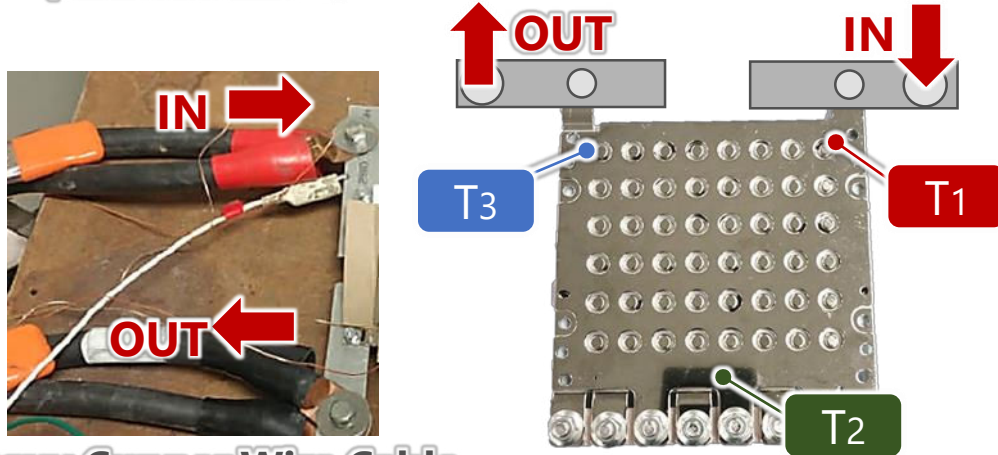
● Simulation

(Ambient: 20.0°C)



● Experiment

(Ambient: 22.7°C)

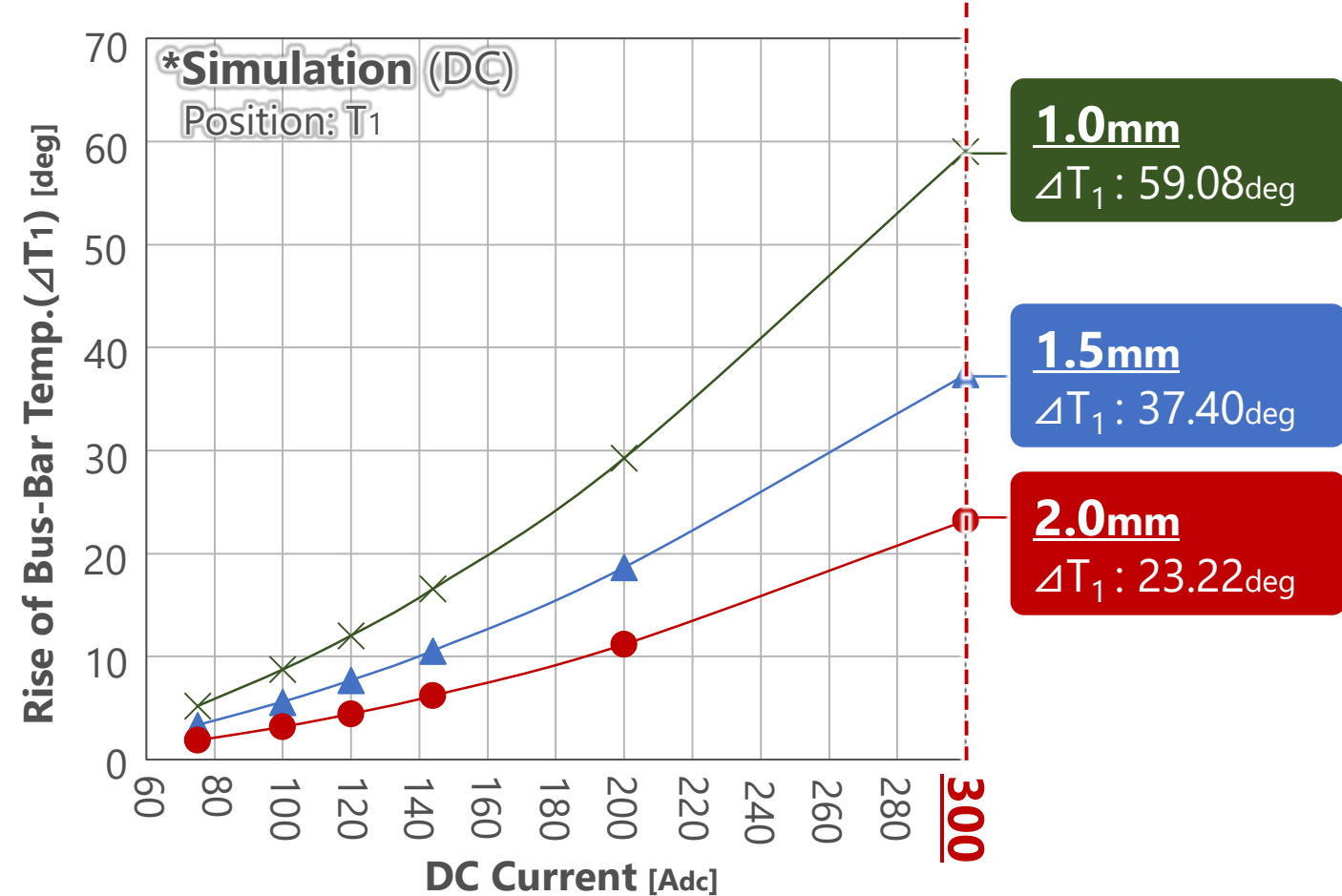
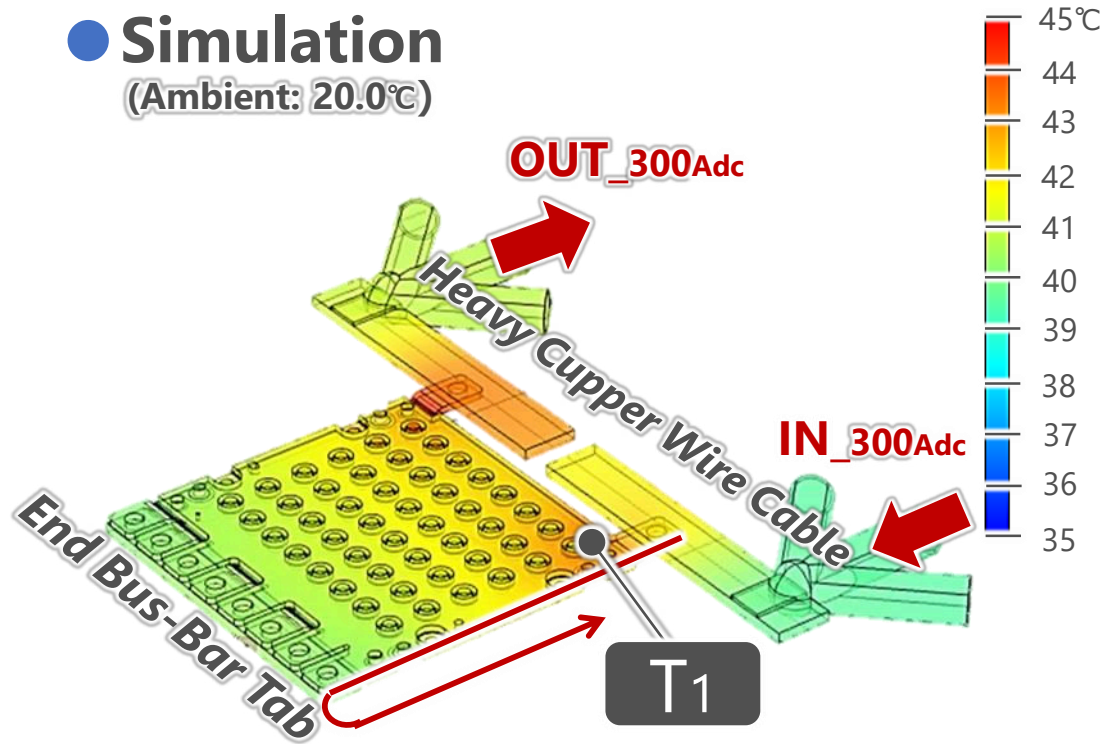


✓ Sim. & Expt. agree each other quite well.

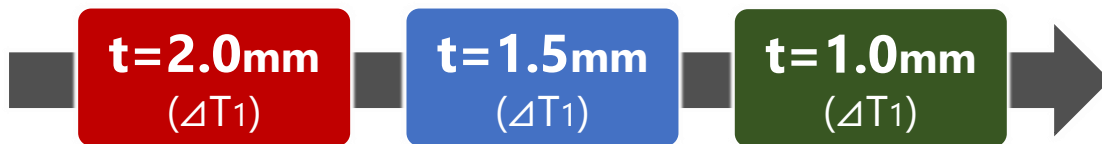
2-3. Change in Copper Thickness of Bus-Bar

● Simulation

(Ambient: 20.0°C)



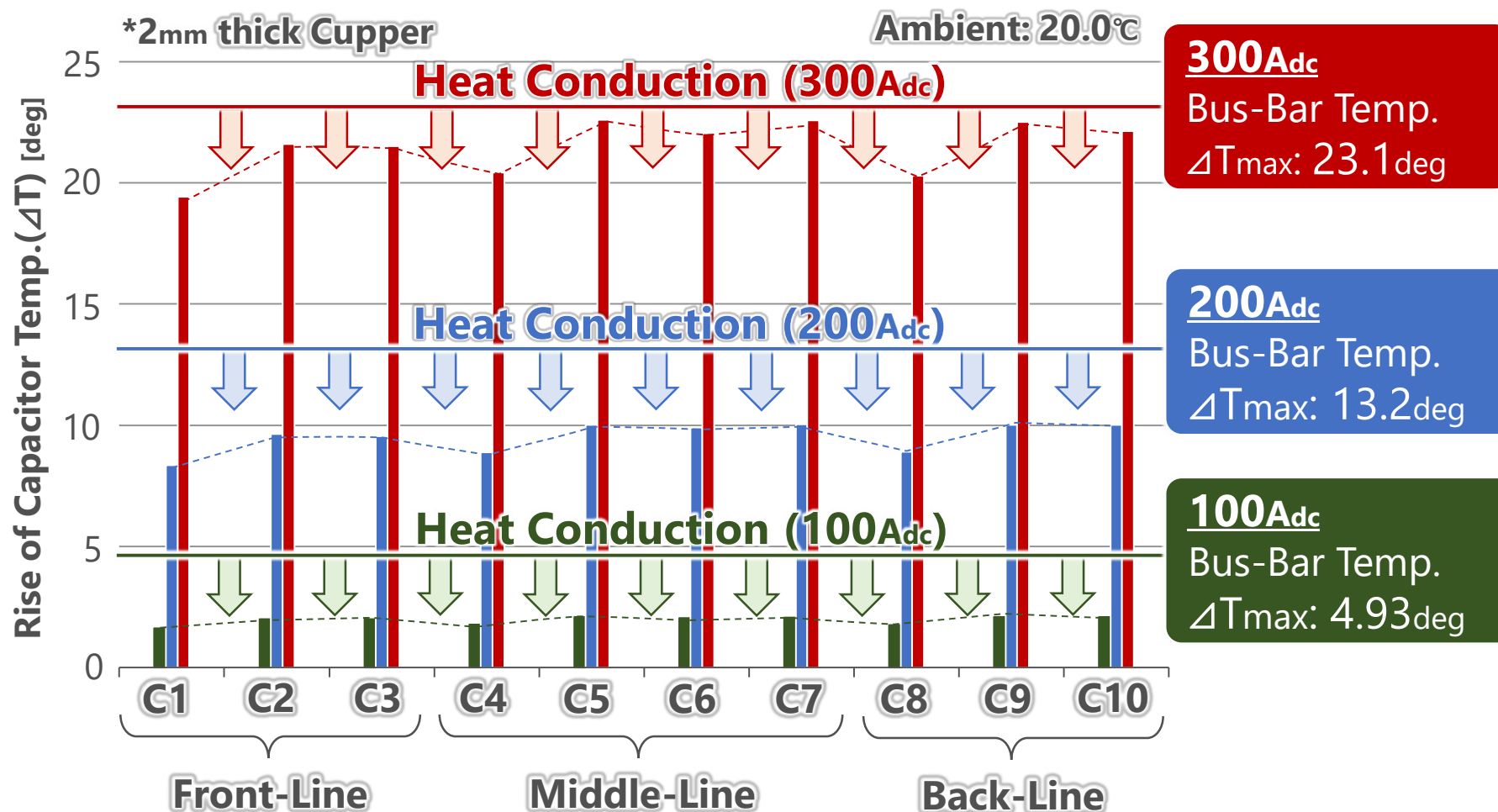
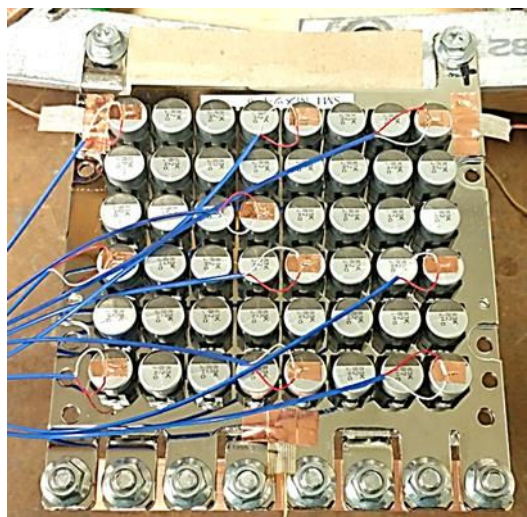
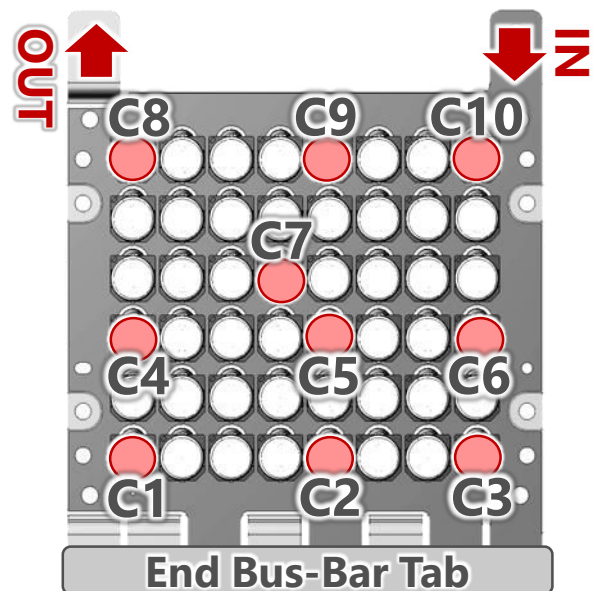
✓ Changing Bus-Bar Thickness



✓ Thin bus-bar has more heat generation.
⇒ Higher ESR value.

2-4. Influence of Heat Conduction from Bus-Bar

● Experiment

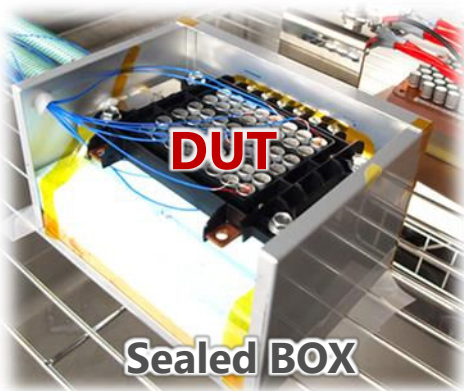
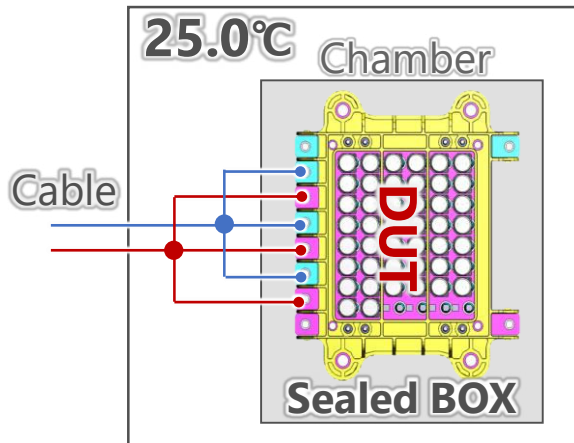


✓ Temperature to capacitors mounted on bus-bar show clearly impacted by conductive heat from bus-bar.

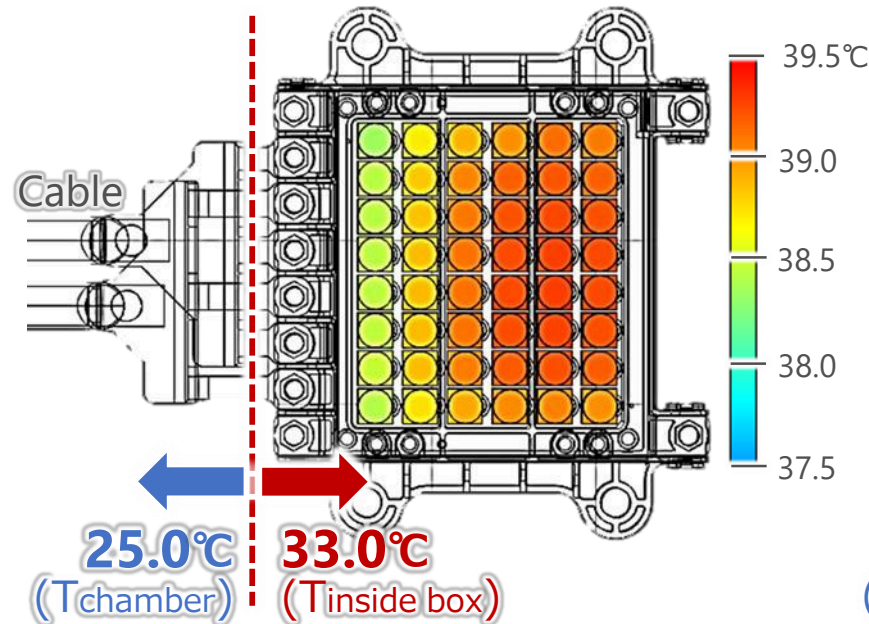
2-5. C-Module Heat Generation (Thermal Sim. & Expt.)

● Conditions

- ✓ Iripple: 90Arms (10kHz)
- ✓ V_{bias} : 52Vdc
- ✓ $T_{chamber}$: 25.0°C

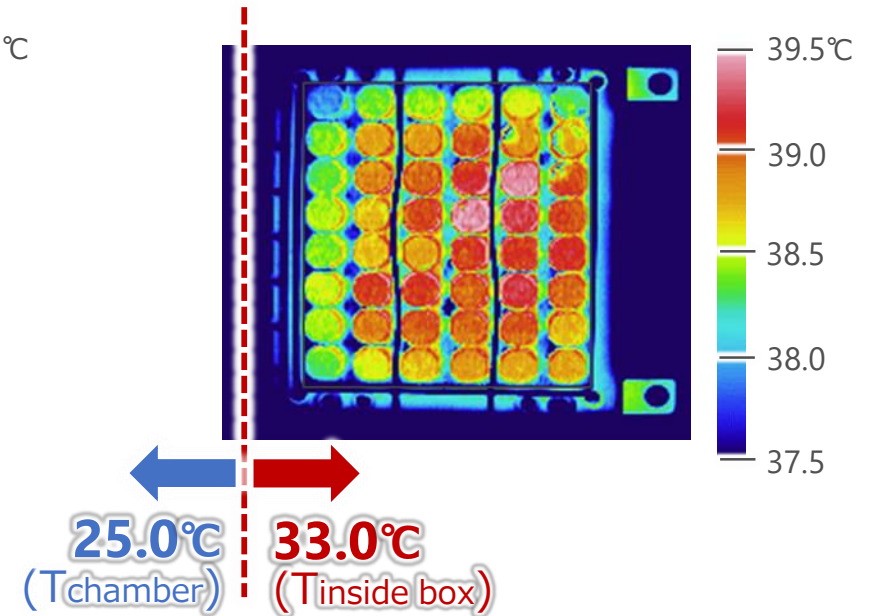


● Simulation



● Experiment

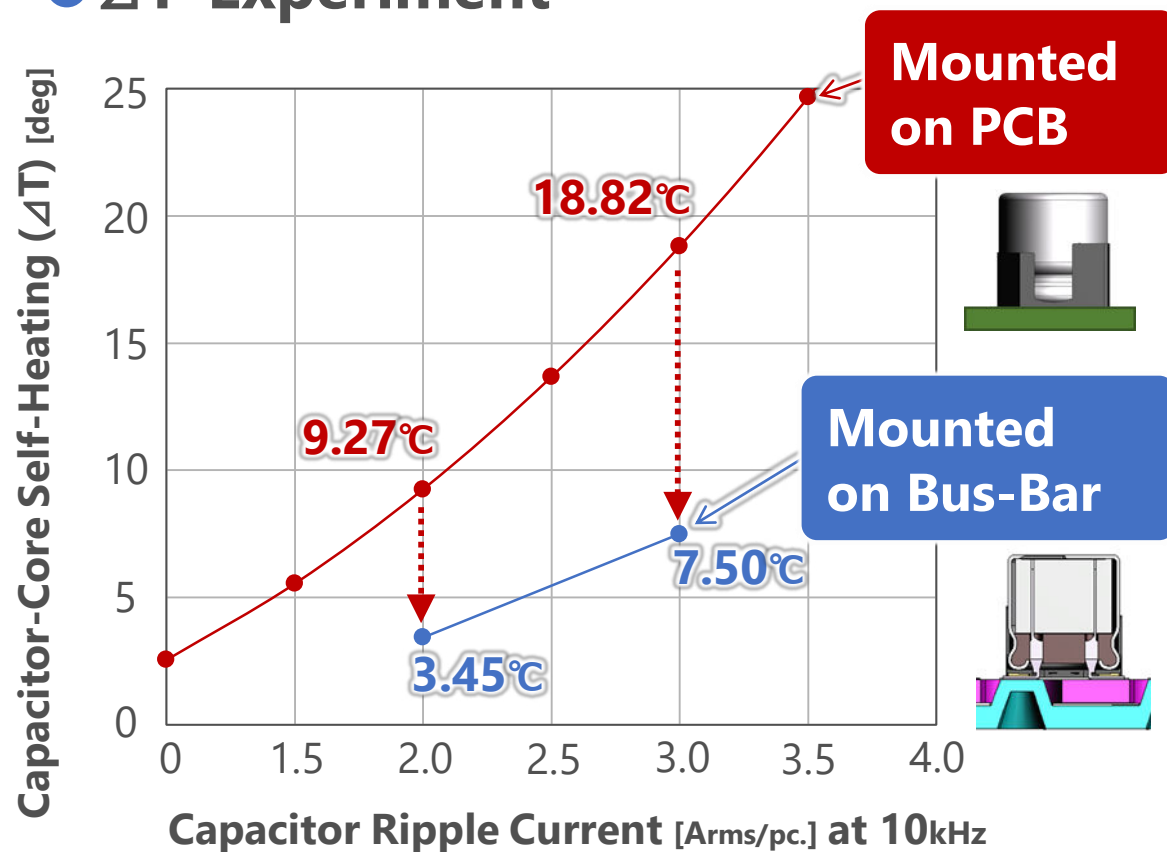
(IR thermometer image)



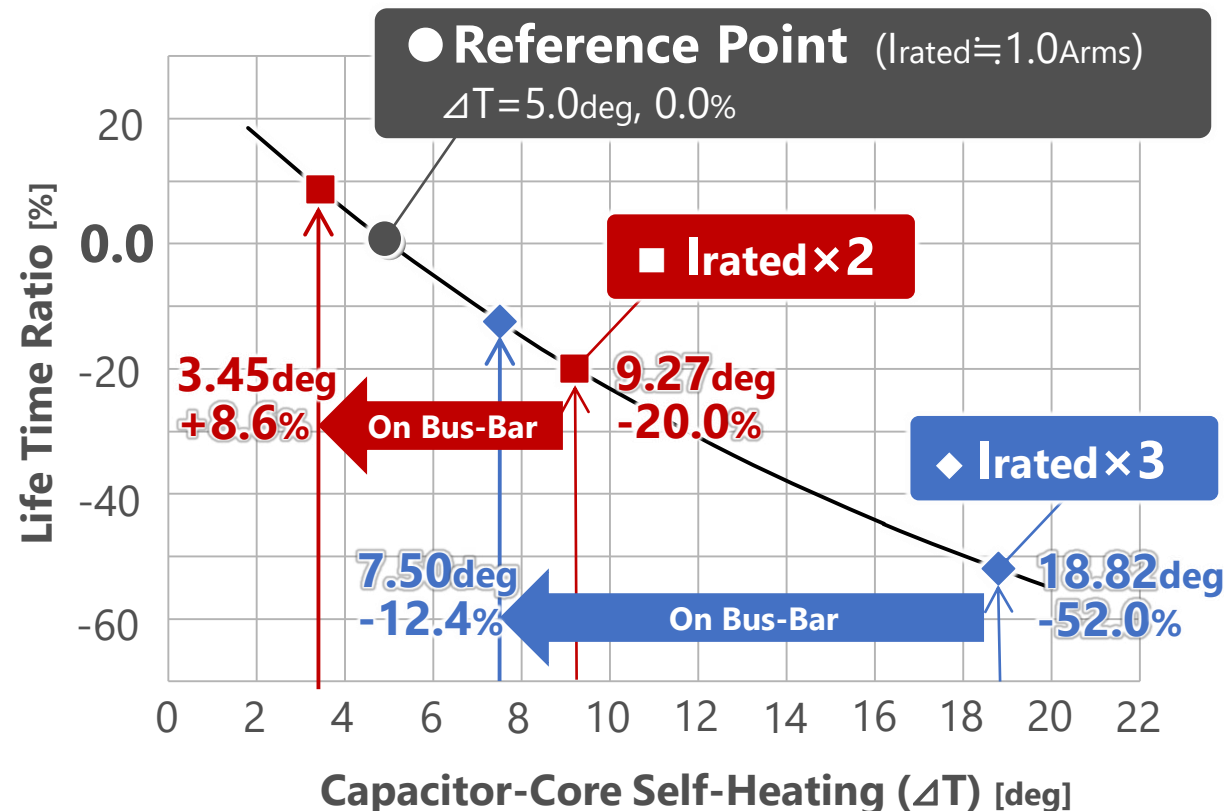
✓ It will be very possible to proceed the thermal management design of C-module with simulation prior to the final packaging design.

2-6. Outcome with Suitable Thermal Mgmt.

● ΔT -Experiment



● Life time Simulation



✓ With effective thermal management

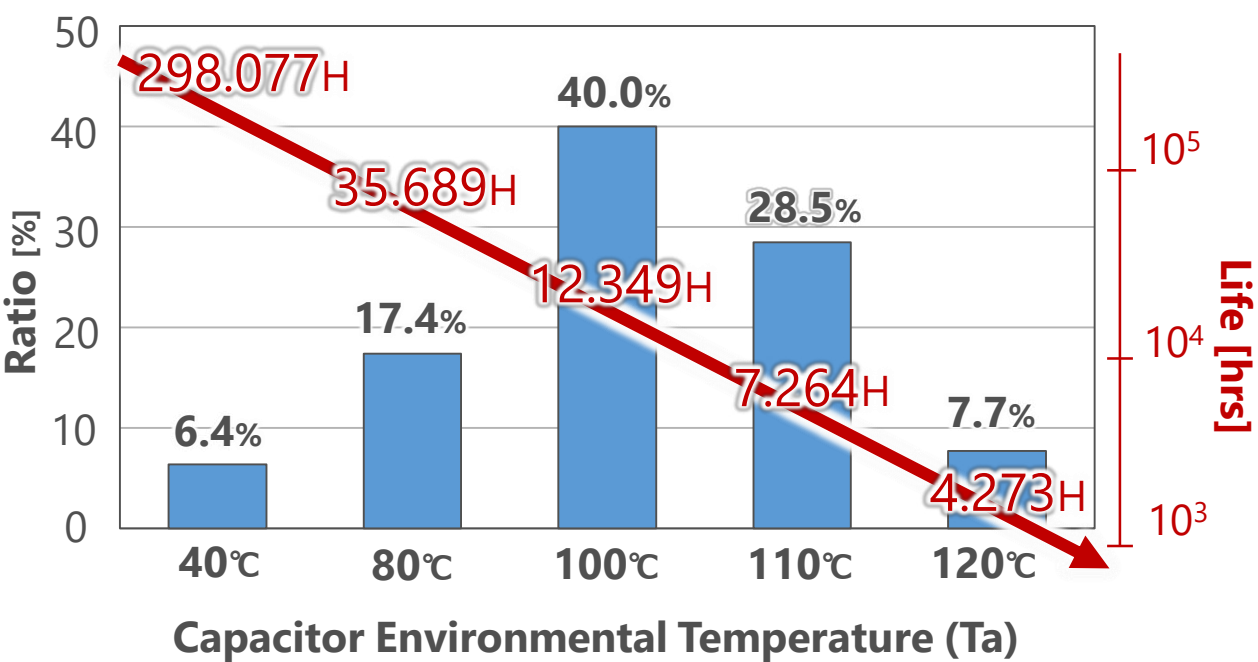
- The core self-heat can be significantly reduce.
- The capacitor life can be improved because of it.

3. Life Analysis (Predicted Life at Worst Case Study)



● Example of Worst Case Scenario

	48pcs. C-Module, 90Arms	
Numbers	16pcs. (1/3)	32pcs. (2/3)
Capacitance	98.6uF/pc. (+20%)	65.6uF/pc. (-20%)
Ripple Current	2.41Arms/pc.	1.61Arms/pc.
ESR	28.88mΩ/pc. (ESRave+4σ)	24.65mΩ/pc. (ESRave)
Self-heat Power	2.68w (56.8%)	2.04w (43.2%)
Core ΔTx	11.20deg	4.98deg

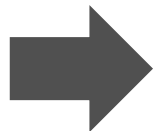


● Life Estimation Formula

$$L(\Delta Tx, Ta) = Lo \cdot K_1^{K_2[(T_0 - Ta) + (\Delta T_0 - \Delta Tx)]} \dots (1)$$

● Combined Life Formula (Miner's Rule)

$$Life(module) = 1 / \sum_{n=1}^m \frac{Ratio_n}{L_n} \dots (2)$$



- Predicted Module Life
10,555hrs
- Typical Life requirements
8,000~9,000hrs

✓ Meets requirements of application!!

4. Conclusions



- **An advanced new concept bus-bar has been proposed as a suitable thermal management solution.**
- **The hybrid capacitor modeling and simulation was performed and compared with actual temperature measurement.**
- **The low profile hybrid capacitor mounted on the new concept bus-bar has fully demonstrated that efficiently handles heat generated by the high ripple current.**
- **Life of new module under the assumption of worst case scenario meet passenger vehicles life requirement.**



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Thank you for your kind attention



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